## TISP4160LP, TISP4180LP SYMMETRICAL TRANSIENT VOLTAGE SUPPRESSORS

APRIL 1987 - REVISED SEPTEMBER 1997

## absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT
Non-repetitive peak on-state pulse current (see Notes 1, 2 and 3)			
8/20 μs (ANSI C62.41, open-circuit voltage wave shape 1.2/50 μs)		100	
5/200 μs (VDE 0433, open-circuit voltage wave shape 2 kV, 10/700 μs)	I <sub>TSP</sub>	50	Α
0.2/310 μs (RLM 88, open-circuit voltage wave shape 1.5 kV, 0.5/700 μs)		38	
5/310 μs (CCITT IX K17, open-circuit voltage wave shape 1.5 kV, 10/700 μs)		38	
Non-repetitive peak on-state current, 50 Hz, 1 s (see Notes 1 and 2)	I <sub>TSM</sub>	2.5	A rms
Initial rate of rise of on-state current, Linear current ramp, Maximum ramp value < 38 A	di <sub>T</sub> /dt	250	A/µs
Junction temperature	T <sub>J</sub>	150	°C
Operating free - air temperature range		0 to 70	°C
Storage temperature range	T <sub>stg</sub>	-40 to +150	°C
Lead temperature 1.5 mm from case for 10 s	T <sub>lead</sub>	260	°C

- NOTES: 1. Above 70°C, derate linearly to zero at 150°C case temperature
  - 2. This value applies when the initial case temperature is at (or below) 70°C. The surge may be repeated after the device has returned to thermal equilibrium.
  - 3. Most PTT's quote an unloaded voltage waveform. In operation the TISP essentially shorts the generator output. The resulting loaded current waveform is specified.

## electrical characteristics, T<sub>J</sub> = 25°C

PARAMETER	TEST CONDITIONS	TISP4160		TISP4180			UNIT		
I ANAMETER		MIN	TYP	MAX	MIN	TYP	MAX	ONIT	
Vz	Reference zener	I <sub>Z</sub> = ± 1mA	± 120			± 145			V
*2	voltage		- 120			± 140			•
∞V <sub>Z</sub>	Temperature coefficient			0.1			0.1		%/°C
\ \Z	of reference voltage			0.1			0.1		707 <b>O</b>
V <sub>(BO)</sub>	Breakover voltage	(see Notes 4 and 5)			± 160			± 180	V
I <sub>(BO)</sub>	Breakover current	(see Note 4)	± 0.15		± 0.6	± 0.15		± 0.6	Α
V <sub>TM</sub>	Peak on-state voltage	$I_T = \pm 5 \text{ A}$ (see Notes 4 and 5)		± 2.2	± 3		± 2.2	± 3	V
I <sub>H</sub>	Holding current	(see Note 4)	± 150			± 150			mA
dv/dt	Critical rate of rise of	(see Note 6)			± 5			± 5	kV/μs
	off-state voltage	(See Note 0)		- 3				κν/μο	
I <sub>D</sub>	Off-state leakage	V <sub>D</sub> = ± 50 V		± 10		± 10	μА		
	current	VD - ± 30 V			± 10			± 10	μΛ
C <sub>off</sub>	Off-state capacitance	$V_D = 0$ $f = 1 \text{ kHz}$		70	150		70	150	pF

- NOTES: 4. These parameters must be measured using pulse techniques,  $t_W = 100 \ \mu s$ , duty cycle  $\leq 2\%$ .
  - 5. These parameters are measured with voltage sensing contacts seperate from the current carrying contacts located within 3.2 mm (0.125 inch) from the device body.
  - 6. Linear rate of rise, maximum voltage limited to 80 %  $\rm V_{\rm Z}$  (minimum).

## thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
R <sub>0JA</sub> Junction to free air thermal resistance			156	°C/W

#### PRODUCT INFORMATION

## PARAMETER MEASUREMENT INFORMATION

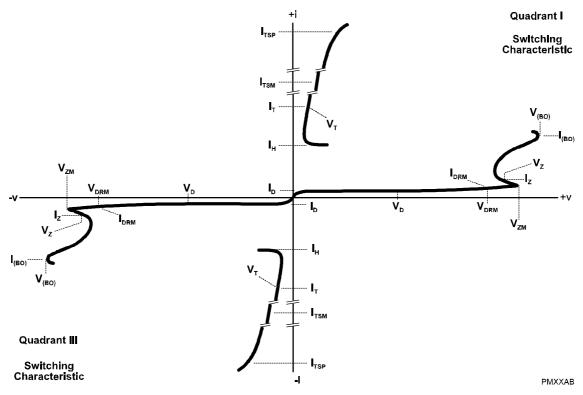


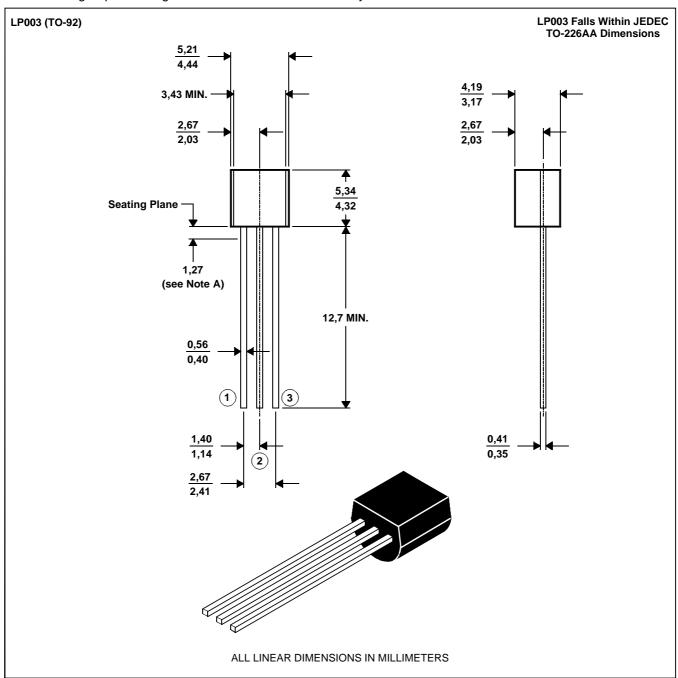
Figure 1. VOLTAGE-CURRENT CHARACTERISTICS FOR TERMINALS A AND B

#### **MECHANICAL DATA**

## LP003 (TO-92)

## 3-pin cylindical plastic package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: Lead dimensions are not controlled in this area.

MDXXAX

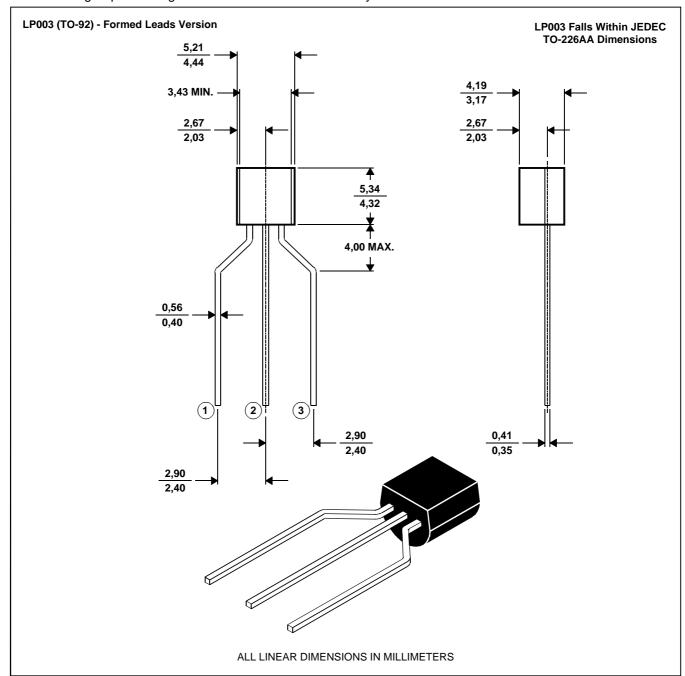
#### PRODUCT INFORMATION

#### **MECHANICAL DATA**

## LP003 (TO-92)

## 3-pin cylindical plastic package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.

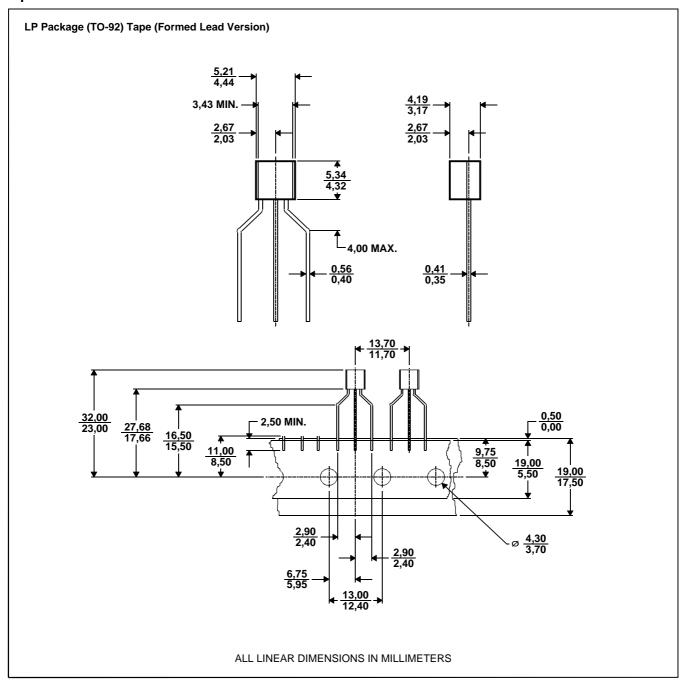


MDXXAR



## **MECHANICAL DATA**

LPR tape dimensions



MDXXAS

APRIL 1987 - REVISED SEPTEMBER 1997

#### **IMPORTANT NOTICE**

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited



# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

# Bourns:

TISP4180LPR TISP4180LPR-S TISP4160LPR-S TISP4160LPR TISP4180LP-S